



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPU80R2K4P7	Issued	27. April 2022
MA#	MA005739943		
Package	PG-TO251-3-23	Weight*	384.41 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.008	0.26	0.26	2621	2621
leadframe	inorganic material	phosphorus	7723-14-0	0.070	0.02		182	
	non noble metal	iron	7439-89-6	0.233	0.06		607	
	non noble metal	copper	7440-50-8	233.116	60.63	60.71	606427	607216
wire	non noble metal	aluminium	7429-90-5	0.196	0.05	0.05	510	510
encapsulation	organic material	carbon black	1333-86-4	0.424	0.11		1103	
	plastics	epoxy resin	-	16.531	4.30		43005	
	inorganic material	silicondioxide	60676-86-0	124.339	32.35	36.76	323455	367563
leadfinish	non noble metal	tin	7440-31-5	7.055	1.84	1.84	18352	18352
solder	non noble metal	tin	7440-31-5	0.029	0.01		75	
	noble metal	silver	7440-22-4	0.036	0.01		93	
	non noble metal	lead	7439-92-1	1.372	0.36	0.38	3570	3738
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com